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Messrs.

Shock Sensor Specification

Part No.: PMLE480W-R

RoHS Compliant

Halogen-Free Compliant

16.Dec. 2010

| Approved by | Kazuki Shimizu | |
|-------------|----------------|--|
| Checked by | Yasuhiro Nakai | |
| Issued by | Akira Oikawa | |

KYOCERA CORPORATION

| No. | Date | Change | Apploved | Checked | Issued |
|-----|--------|-------------------|----------|----------|----------|
| 00 | 16.Dec | The first edition | Kazuki | Yasuhiro | Akira |
| | 2010 | | Shimizu | Nakai | Oikawa |
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1.Scope

This specification shall cover the characteristics of the shock sensor.

Preliminary

2. Kyocera's Type Name

PMLE480W-R

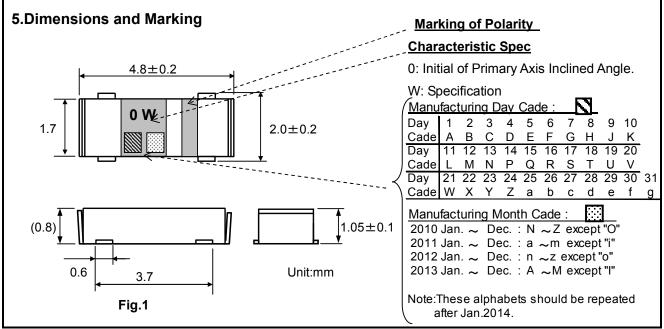
3. Customer's Type Name

4. Electrical Characteristics

| Items | Specifications | |
|---------------------------------|---------------------------------------|--|
| 4-1 Primary Axis Inclined Angle | 0 ± 3degree | |
| 4-2 Capacitance | 890pF ± 30%, at 1Vrms, 1kHz | |
| 4-3 Charge Sensitivity | 0.608 pC/G ± 15% | |
| 4-3 Gharge Sensitivity | under vibration at 200Hz, 2G | |
| 4-4 Insulation Resistance | 0.5Gohm minimum, at 10VDC after 1min. | |
| 4-5 Resonant Frequency | 19.5 ± 3.5kHz | |
| 4-6 Non-linearity | 5% maximum, under vibration at 25G | |
| 4-7 Charge Sensitivity | Ta:70°C 7.7±3.0% | |
| Temperature Drift | Ta:0°C -4.2±2.0% | |
| remperature Difft | under vibration at 200Hz, 2G | |

<Measurement Condition>

The reference temperature shall be 25 °C ±5°C.

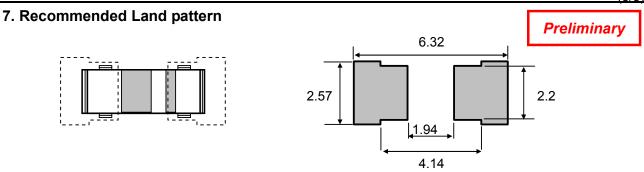


CIRCUIT COMPONENT DIVISION
PIZ SECTION

| Items | Conditions | Prelimi |
|------------------------|--|------------|
| | | |
| 6-1.High Temperature | Keep in a chamber at $85 \pm 2^{\circ}$ C for 1000 +12/-0 hours, and then kee | • |
| Storage Test | temperature for 1 hour. The characteristics of shock sensor shall | meet the |
| | specifications. | |
| 6-2.Low Temperature | Keep in a chamber at $-40 \pm 2^{\circ}$ C for 1000 +12/-0 hours, and then | • |
| Storage Test | room temperature for 1 hour. The characteristics of shock sensor s the specifications. | shall meet |
| 6-3.Moisture | Keep in a chamber at 90 to 95 % R.H. and 60 \pm 2°C for 500 +12/ | /-0 hours, |
| Resistance Test | and then keep at room temperature for 1 hour. The characteristics | of shock |
| | sensor shall meet the specifications. | |
| 6-4.Temperature | Apply 100 thermal cycles with the following temperatures: | |
| Cycling Test | - upper temperature 85°C for 20 minutes and transfer time 10 mi | inutes |
| | - lower temperature -40°C for 20 minutes and transfer time 10 m | ninutes |
| | - total cycle time is 1hour | |
| | and then left at room temperature for 1 hour. The characteristics | of shock |
| | sensor shall meet the specifications. | |
| 6-5.Mechanical Shock | After applying the acceleration at 29430m/sec ² {3000G} in each of | X, Y and |
| Test | Z axis (each 3 times). The characteristics of shock sensor shall | meet the |
| | specifications. | |
| 6-6.Solderability Test | At first, being soaked in the Methanol solution containing Ro | sin for 5 |
| | seconds and then being dipped in a bath of Pb/Sn solder at 250 \pm | 5°C for 4 |
| | ±0.5 seconds. The surface of the electrode terminal shall be solde | ered more |
| | than 95%. | |
| 6-7.Resistance to | Pre-heat temperature is 150 to 180°C for 1 minute. High temperature | ure is 250 |
| Soldering Heat Test | \pm 5°C, over 200°C for 20 seconds max.(2times). Then keep | at room |
| | temperature for 1 hour. The characteristics of shock sensor shall | meet the |
| | specifications. | |
| 6-8.Board Flex Test | After soldered on the circuit board specified as below, then the lo | ad which |
| | cause 3 mm bend to the board is applied. The characteristics | of shock |
| | sensor shall meet the specifications. The shock sensor cause no | defect in |
| | the appearance. (Circuit Board: FR4, 100 x 40 x 1.6) | |
| | R230 J | |
| | 45 45 5.57 | |

<Measurement Condition>

The reference temperature shall be 25°C±5°C.



Unit: (mm)

Fig.2 Recommended Land pattern

8. Recommended Convection Reflow profile

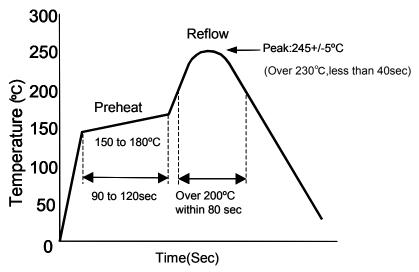
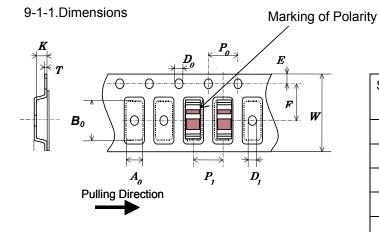


Fig.3 Recommended Convection Reflow profile

9. Taping Specifications

9-1.CarrierTape



| Linit | : (mm) |
|-------|---------------------|
| UIIIL | . (<i> </i> |

| Sym | Dimensions | Sym | Dimensions |
|-------|----------------|----------------|---------------|
| bol | Dimensions | bol | Dimensions |
| A_0 | 2.25 ± 0.1 | P_0 | 4.0 ± 0.1 |
| B_0 | 4.4 ± 0.1 | P ₁ | 4.0 ± 0.1 |
| W | 12.0 +0.3/-0.1 | D_0 | 1.5 +0.1/-0 |
| E | 1.75 ± 0.1 | K | 1.25± 0.1 |
| F | 5.5± 0.05 | Т | 0.3 ± 0.05 |

Fig.4 Emboss Carrier Tape Dimensions

(4/5)

9-2. Taping

9-2-1. Taping Quantity

Preliminary

One reel of the carrier tape shall pack 3500 pcs. Shock sensor shall be contained in pocket continuously.

9-2-2. Dimensions

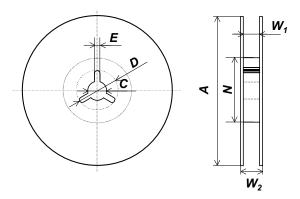


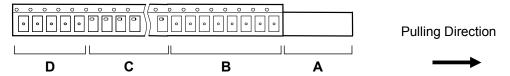
Fig.5 Reel

Unit: (mm)

| Symbol | A | N | W ₁ | W_2 |
|------------|---------|--------|-----------------------|-----------|
| Dimensions | 180±5.0 | 60min. | 12.5 +2.0/-0.0 | 20.5 max. |
| | | | | |
| Symbol | С | D | E | |

9-2-3. Leader and Blank Pocket

Package shall consist of leader, blank pocket and loaded pocket as follows. (fig.6)



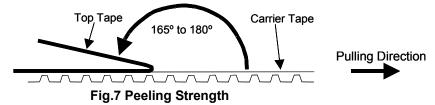
- A) Leader
- B) Blank Pocket (160mm Min.)

A+B: 400mm to 560mm

- C) Load Pocket
- D) Blank Pocket (40 to 190mm)

Fig.6 Packing Method

Peeling load of top tape shall be 0.1N {10gf} to 0.7N {70gf} from Carrier Tape.



CIRCUIT COMPONENT DIVISION PIZ SECTION

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9-2-4. Reel label

A reel label shall be contained as below: (Based on EIAJ C-3 format)

Preliminary

- A) Customer P/N
- B) Lot No.
- C) Quantity
- D) Shipping date
- E) Vender Name

9-2-5. Exterior Package label

Shock sensor shall be packed properly to avoid defect in transportation and the marking of exterior package shall be contained as below:

- A) Name of Customer
- B) P/O No.
- C) Customer P/N
- D) Lot No.
- E) Quantity
- F) Shipping Date
- G) Vender Name

10. The agreement of this specifications

Should any part of the content of this specification become questionable, it shall be settled by mutual deliberations.

11. Remarks on Usage

- A) This part can use only reflow soldering.
- B) Not washable
- C) Maximum temperature is 280 degree.

12.RoHS Compliant

- A) Sensor Case: LCP(liquid crystal polymer)
- B) Terminal: Bronze with phosphate (thickness 100 um)

Plating: Cu(1-2um), Ag(1-3um)

C) Element: Piezo Ceramic, contains lead-oxide, however, piezo-electronic devices are exempted from RoHS compliant requirement of article 4(1).

(Refer to Annex, Section 7)

All materials meet to RoHS Compliant.

13. Halogen-Free Compliant

- A) Bromine(Br) <900ppm(0.09%)
- B) Chlorine(CI) <900ppm(0.09%)
- C)Total concentration of Chlorine(CI) + Bromine(Br) < 1500ppm(0.15%)
- D)Antimony Trioxide(Sb2O3) <1000ppm(0.1%)
- E)Red Phosphorus <1000ppm(0.1%)

All materials meet to Halogen-Free Compliant.